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SOLID-STATE IMAGING DEVICE AND
METHOD FOR PRODUCING THE SAME

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BACKGROUND OF THE INVENTION

1. FIELD OF THE INVENTION:

5 The present invention relates to a solid-state imaging device, and in particular to a solid-state imaging device structured so as to enhance the sensitivity of a light reception section thereof and a method for producing such a device.

10 2. DESCRIPTION OF THE RELATED ART:

15 In recent years, the transmission and reception of images is becoming indispensable to portable information devices and the like including cellular phones. So-called solid-state imaging devices such as CCDs are used for imaging purposes while liquid crystal panels are used for displaying images. In the field of solid-state imaging devices, CMOS image sensors based on a so-called CMOS logic process, which is typically used for producing a normal integrated circuit, are widely developed with a view to achieving low power consumption and a low cost. As in the case of CCDs, the demand for higher resolution and miniaturization has necessitated CMOS image sensors having reduced pixel size, as well as having a reduced area of the light reception section, and

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a reduced aperture size in a light shielding film. However, since CMOS image sensors have so far been developed based on the so-called logic process, very little attention has been paid to the optical characteristics of CMOS image sensors, such as reflection or refraction at interfaces between the layers of multi-layered films incorporated therein. Therefore, it is difficult with CMOS image sensors to efficiently converge incident light and obtain sufficient sensitivity.

A conventional solid-state imaging device, in particular a CMOS image sensor, will be described with reference to Figure 5. A light reception section 12 is formed on a top surface of a silicon substrate 11 for converting incident light ($h\nu$) to an electric charge. An interlaminar insulation film 13 is formed on the silicon substrate 11 for electrically isolating a first metal layer 18, a second metal layer 19, and a light shielding film 14 from one another. The light shielding film 14 is formed so as not to overlie a light reception face of the light reception section 12, so that light incident on the interlaminar insulation film 13 does not fall anywhere except the light reception section 12. A

passivation film 15 is formed on the light shielding film 14 and on the interlaminar insulation film 13 which is present within an aperture of the light shielding film 14. The passivation film 15 provides moisture-
5 resistance, chemical resistance, and improved barrier properties against impurities such as Na ions, oxygen, etc., and metals. A planarization film 16 is formed on the passivation film 15. A microlens 17 is formed for converging light which is incident on the planarization
10 film 16. As the interlaminar insulation film 13, a deposited film such as a P (plasma CVD)-SiO₂ film, an NSG film (a silicon oxide film containing no impurities), a BPSG film (a silicon oxide film containing phosphorus and boron) or the like is used. As the passivation film 15,
15 a monolayer film, such as a P (plasma CVD)-SiN film, or a deposited film composed of a P-SiN film and a PSG film (a silicon oxide film containing phosphorus), is generally used. The planarization film 16 is generally composed of an acrylic material. In the case of a color
20 solid-state imaging device, an acrylic material and a color filter are utilized as the planarization film 16. In conventional CMOS image sensor structures, the passivation film 15 has a stepped portion as described above, which prevents the convergence of light. When such

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a structure is adapted for higher resolution and miniaturization, the stepped portion of the passivation film 15 causes a decrease in the amount of light converged on the light reception section 12, thereby making it difficult to obtain sufficient sensitivity.

A method for producing the above-described device will now be described with reference to Figure 6. The light reception section 12 is formed in the silicon substrate 11 through ion implantation, heat treatment, etc. After forming a polycrystalline silicon film and a silicide film on the silicon substrate 11 by using a CVD technique, a gate electrode (not shown) is formed by patterning, etching, or the like. Thereafter, a BPSG film is deposited as the interlaminar insulation film 13 by a CVD technique. When the BPSG film receives heat treatment at a high temperature, the film becomes fluid so that its surface can be flattened. By taking advantage of such characteristics of the BPSG film, the surface of the BPSG film is flattened so as to facilitate the formation of the first metal layer 18. The first metal layer 18 is formed by depositing TiN, Al or the like on the BPSG film by using a sputtering or CVD technique. Upon the first metal layer 18, the P-SiO₂ film is deposited as

the interlaminar insulation film 13 by using a CVD technique and the surface thereof is flattened by chemical machine polishing. Thereafter, as in the case of the first metal layer 18, a thin film of TiN, Al, or the like is formed as the second metal layer 19 by using a sputtering or CVD technique. Similarly, upon the second metal layer 19, a P-SiO₂ film is deposited as the interlaminar insulation film 13 by using a CVD technique and the surface thereof is flattened by the chemical machine polishing. Thereafter, TiN, Al, or the like is deposited as the light shielding film 14 by using a sputtering or CVD technique, and the resultant film is patterned and etched so as not to overlies the light reception section 12. Upon the light shielding film 14, a P-SiN film is deposited as the passivation film 15 by using a CVD technique or the like. The planarization film 16 is formed by applying an acrylic material to the passivation film 15. In the case of a color solid-state imaging device, an acrylic material is applied; a color filter is formed; and then the acrylic material is further applied thereto as a protection coating, thereby completing the planarization film 16. Thereafter, a lens material is applied and the microlens 17 is formed by patterning and heat treatment.

In a conventional solid-state imaging device shown as Figure 5A, the refractive index of the P-SiN film used for the passivation film 15 is about 2.0 while the refractive index of the acrylic material used for the planarization film 16 is about 1.5 to 1.6. In the case where the refractive index of the passivation film 15 is higher than that of the planarization film 16, when light falls onto an edge of the passivation film 15, the incident light is not converged on the light reception section 12 but rather refracted so as to travel outside the light reception section 12 toward the first metal layer 18 or the second metal layer 19 since the edge of the passivation film 15 has a rounded shape. As shown in an enlarged view of Figure 5B, when light falls onto the flat top surface of the stepped portion, total internal reflection can occur at an interface between the planarization film 16 and a face of the passivation film 15 parallel to a side face of the light shielding film 14, depending on the incident angle of the light, since the refractive index of the passivation film 15 is higher than that of the planarization film 16. The incident light passes along the face of the passivation film 15 parallel to the side face of the light shielding

film 14 so that the light is not converged on the light reception section 12. As described above, in the conventional structure shown as Figure 5A, any light incident on a portion of the passivation film 15 neighboring the side face of the light shielding film 14 is not converged on the light reception section 12. Therefore, the effective aperture size of the light shielding film 14 is smaller than the actual aperture size by an amount corresponding to the thickness of the passivation film 15.

The light reception face of the light reception section 12 used to be sufficiently large relative to the stepped portion of the passivation film 15. However, due to the reduced pixel size which is necessitated for improved resolution and miniaturization, the light reception face of the light reception section 12 is becoming smaller and the aperture of the light shielding film 14 is also becoming narrower. Therefore, the ratio of the amount of light incident on the stepped portion of the passivation film 15 to the amount of light incident on the aperture of the light shielding film 14 increases, thereby making it difficult to obtain sufficient sensitivity. However, the passivation film 15 can not

be omitted because the passivation film 15 plays an important role in providing moisture-resistance, chemical resistance and/or improved barrier properties against impurities such as Na ions, oxygen, etc., and
5 metals.

The effect of the stepped portion of the passivation film 15 on the numerical aperture of the light shielding film 14 will now be described in detail.
10 Provided that the sensitivity deteriorates by an amount corresponding to the thickness of the passivation film 15, the aperture size can be represented as (pixel size) - (width of the light shielding film) - (2 × thickness of the passivation film 15). For example, in the case where
15 the width of the light shielding film 14 is 1.5 μm, and the thickness of the passivation film 15 is 0.5 μm, given a pixel size of 10 μm × 10 μm, the aperture of the light shielding film 14 is calculated to be $10 - 1.5 - (0.5 \times 2) = 7.5$ μm, and therefore, the numerical aperture is 75%.
20 Similarly, given a pixel size of 5 μm × 5 μm, the aperture of the light shielding film 14 is calculated to be $5 - 1.5 - (0.5 \times 2) = 2.5$ μm, and therefore, the numerical aperture is 50%. Starting from the above one-dimensional calculation, it will be seen that the numerical aperture

area as calculated in a two-dimensional manner gives rise to an even greater difference in the size (area) between the aperture and each pixel. The reduction in the numerical aperture of the light shielding film 14 is highly detrimental to the ratio of light incident on the light reception face of the light reception section 12; this effect is more detrimental than any reduction in the numerical aperture of layers below the light shielding film 14.

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SUMMARY OF THE INVENTION

According to one aspect of this invention, there is provided a solid-state imaging device, including a semiconductor substrate, a light shielding section having an aperture for partially shielding light incident on a surface of the semiconductor substrate, a light reception section for converting the light which is incident on the surface of the semiconductor substrate through the aperture to an electric charge, and a passivation section having a substantially flat top surface and overlying the light shielding section, the light reception section and the aperture.

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Variable	Mean	Standard deviation	Minimum	Maximum
Age	35.5	10.5	20	55
Gender	0.5	0.5	0	1
Marital status	0.5	0.5	0	1
Education	12.5	1.5	10	15
Income	15.5	5.5	10	25
Health status	0.5	0.5	0	1
Smoking status	0.5	0.5	0	1
Alcohol consumption	0.5	0.5	0	1
Exercise frequency	0.5	0.5	0	1
Stress level	0.5	0.5	0	1
Sleep quality	0.5	0.5	0	1
Work satisfaction	0.5	0.5	0	1
Life satisfaction	0.5	0.5	0	1

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shielding section, the light reception section and the aperture, and the method includes the steps of forming a thin film used for forming the passivation section on the light shielding section and the aperture, and
5 flattening a surface of the thin film to form the passivation section by chemical machine polishing.

According to still another aspect of the invention, there is provided a method for producing a solid-state
10 imaging device which includes a semiconductor substrate, a light shielding section having an aperture for partially shielding light incident on a surface of the semiconductor substrate, a light reception section for converting the light which is incident on the surface of the
15 semiconductor substrate through the aperture to an electric charge, and a passivation section having a substantially flat top surface and overlying the light shielding section, the light reception section and the aperture, and the method includes the steps of forming
20 a thin film used for forming the passivation section on the light shielding section, applying an SOG film to the thin film used for forming the passivation section, and performing an etchback technique under a condition that a selective ratio of the SOG film to the thin film used

for forming the passivation section is about 1 to 1.

According to still another aspect of the invention,
there is provided a method for producing a solid-state
5 imaging device which includes a semiconductor substrate,
a light shielding section having an aperture for shielding
light incident on a surface of the semiconductor substrate,
a light reception section for converting the light which
is incident on the surface of the semiconductor substrate
10 through the aperture to an electric charge, a passivation
section having a substantially flat top surface and
overlying the light shielding section, the light
reception section and the aperture, and an insulation
section having a substantially flat top surface which is
15 interposed between the passivation section and the light
shielding section, and the method includes the steps of
forming the insulation section on the light shielding
section, flattening a surface of the insulation section
by chemical machine polishing, and forming the
20 passivation section so as to have the substantially flat
top surface by depositing a material used for forming the
passivation section on the insulation section.

According to still another aspect of the invention,

there is provided a method for producing a solid-state imaging device which includes a semiconductor substrate, a light shielding section having an aperture for partially shielding light incident on an surface of the semiconductor substrate, a light reception section for converting the light which is incident on the surface of the semiconductor substrate through the aperture to an electric charge, a passivation section having a substantially flat top surface and overlying the light shielding section, a light reception section and the aperture, and an insulation section having a substantially flat top surface which is interposed between the passivation section and the light shielding section, and the method includes the steps of forming the insulation section so as to have the substantially flat top surface by applying an SOG film to the light shielding section and the aperture, and forming the passivation section so as to have the substantially flat top surface by depositing a material used for forming the passivation section on the insulation section.

In order to achieve the above-described objectives, according to the present invention, a passivation film is deposited on an interlaminar

insulation film so as to have a thickness which is greater than that of a light shielding film. Thereafter, a portion of the thickly deposited passivation film is removed, to such an extent that the light shielding film is not exposed, by chemical machine polishing or by using an etchback technique after applying an SOG to the passivation film. Thus, a surface of the passivation film is flattened.

Alternatively, a silicon oxide-based insulation film is thickly deposited on the light shielding film and the interlaminar insulation film in the manner described above. Thereafter, a portion of the resultant film is removed, to such an extent that the light shielding film is not exposed, by using chemical machine polishing. Thus, a surface of the film is flattened. A passivation film is then deposited on a top surface of the silicon oxide-based insulation film. Since the top surface of the silicon oxide-based insulation film is flat, the top surface of the passivation film, which is deposited on the insulation film, also becomes flat. Therefore, the passivation film is prevented from having any stepped portion, which is one problem associated with a conventional passivation film.

Alternatively, an SOG film is applied on the light shielding film and the interlaminar insulation film. The passivation film is then deposited on a top surface of the SOG film. Since the top surface of the SOG film is flat, the top surface of the passivation film, which is deposited on the SOG film, also becomes flat. Therefore, the passivation film is prevented from having any stepped portion, which is one problem associated with a conventional passivation film.

As described above, through the use of the aforementioned techniques, according to the present invention, the passivation film is prevented from having any stepped portion, which is one problem associated with a conventional passivation film. Therefore, a component of light which would otherwise fall onto stepped areas to be refracted in directions away from the light reception section can be converged on the light reception section. Thus, the imaging device according to the present invention can be adapted for higher resolution and miniaturization.

Thus, the invention described herein makes

possible the advantages of: (1) providing a solid-state imaging device which can converge incident light on a light reception section thereof due to the absence of stepped portions on a passivation film; and (2) providing
5 a method for producing such a solid-state imaging device.

These and other advantages of the present invention will become apparent to those skilled in the art upon reading and understanding the following detailed
10 description with reference to the accompanying figures.

BRIEF DESCRIPTION OF THE DRAWINGS

Figure 1 is a cross-sectional view of a solid-state imaging device according to Example 1 of the present
15 invention.

Figure 2 is a cross-sectional view of a solid-state imaging device according to Example 2 of the present
20 invention.

Figures 3A, 3B, 3C, 3D, 3E, and 3F are cross-sectional views illustrating production steps of a solid-state imaging device according to Example 1 of the

present invention.

Figure 4A, 4B, 4C, 4D, 4E, 4F and 4G are cross-sectional views illustrating production steps of a solid-state imaging device according to Example 2 of the present invention.

Figure 5A is a cross-sectional view illustrating a structure of a conventional solid-state imaging device.

Figure 5B is a partial enlarged view of Figure 5A.

Figures 6A, 6B, 6C, 6D, 6E, and 6F are cross-sectional views illustrating production steps of a conventional solid-state imaging device.

DESCRIPTION OF THE PREFERRED EMBODIMENTS

Examples of the present invention will be described below in detail with reference to drawings.

(Example 1)

A basic structure of Example 1 of the present invention is shown in Figure 1. As shown in Figure 1,

5 a light reception section 2 for converting incident light
to an electric charge is formed on a top surface of a
silicon substrate 1. An interlaminar insulation film 3
for electrically isolating a first metal layer 8, a second
10 metal layer 9, and a light shielding film 4 from one
another is formed on the silicon substrate 1. The light
shielding film 4 is formed on the interlaminar insulation
film 3 without overlying, a light reception face of the
light reception section 2, so that incident light does
15 not fall anywhere except the light reception section 2.
A passivation film 5 is formed on the light shielding
film 4 and on the interlaminar insulation film 3 which
is present within an aperture of the light shielding
film 4 in order to provide moisture-resistance, chemical
20 resistance, and improved barrier properties against
impurities such as Na ions, oxygen, etc., and metals. A
portion of the passivation film 5 is removed, to such an
extent that the light shielding film 4 is not exposed,
by using chemical machine polishing or an etchback
technique. Thus a surface of the passivation film is
flattened. A planarization film 6 is formed on the
passivation film 5. A microlens 7 is formed for
converging light which is incident on the planarization
film 6. In Example 1, the passivation film 5 may be in

the form of a SiN-based monolayer film, or a deposited film composed of a SiN-based film, having a refractive index of about 2.0. An acrylic material is used for the planarization film 6, having a refractive index of about 1.5 to 1.6.

In conventional structures, the passivation film 15 would have a stepped portion as shown in Figure 5A and 5B. Light incident on the stepped portion is refracted in directions away from the light reception section, due to the different refractive index of an edge of the stepped portion. Since the refractive index of the passivation film 15 is higher than that of the planarization film 16, total internal reflection occurs at an interface between the planarization film 16 and a face of the passivation film 15 parallel to a side face of the light shielding film 14, so that incident light is not converged on the light reception section 12. However, in the structure according to Example 1 of the present invention, the passivation film 5 is thickly deposited and a top surface thereof is flattened by chemical machine polishing or an etchback technique, so that any refraction of incident light associated with a stepped portion, as in the case of the passivation film 15

of conventional structures, does not occur. As a result, most of light converged by the microlens 7 is converged on the light reception section 2.

5 A method for producing a solid-state imaging device according to Example 1 of the present invention will now be described with reference to Figure 3A, 3B, 3C, 3D, 3E, and 3F. The light reception section 2 is formed in the silicon substrate 1 through ion
10 implantation, heat treatment, etc. (Figure 3A). After forming a polycrystalline silicon film and a silicide film on the silicon substrate 1 by using a CVD technique, a gate electrode (not shown) is formed by patterning, etching, or the like. Thereafter, a BPSG film is
15 deposited so as to have a thickness of about 5000 Å to 15000 Å as the interlaminar insulation film 3 by a CVD technique. By subjecting the BPSG film to heat treatment at about 850 to 950°C, its surface is flattened so as to facilitate the formation of the first metal layer 8. The
20 first metal layer 8 is formed by depositing TiN to a thickness of about 300 Å to 1000 Å and Al to a thickness of about 3000 Å to 10000 Å on the BPSG film by using a sputtering or CVD technique (Figure 3B). Upon the first metal layer 8, a P-SiO₂ film having a thickness of about

20000 Å to 25000 Å is deposited as the interlaminar insulation film 3 by using a CVD technique, and a thickness of about 10000 Å is removed from the resultant film by chemical machine polishing, thereby flattening the film surface. Thereafter, as in the case of the first metal layer 8, TiN having a thickness of about 300 Å to 1000 Å and Al having a thickness of about 3000 Å to 10000 Å are deposited as the second metal layer 9 by using a sputtering or CVD technique (Figure 3C). Similarly, upon the second metal layer 9, a P-SiO₂ film having a thickness of about 20000 Å to 25000 Å is deposited as the interlaminar insulation film 3 by using a CVD technique and a thickness of about 10000 Å is removed from the resultant film by chemical machine polishing, thereby flattening the film surface. Thereafter, TiN having a thickness of about 300 Å to 1000 Å and Al having a thickness of about 3000 Å to 10000 Å are deposited as the light shielding film 4 by using a sputtering or CVD technique, and the resultant film is patterned and etched so as not to overlie the light reception section 2 (Figure 3D). Upon the light shielding film 4, a P-SiN film having a thickness of 20000 Å is deposited as the passivation film 5. Thereafter, a thickness of about 10000 Å is removed from the P-SiN film by chemical machine

polishing, thereby flattening the film surface (Figure 3E). In another way of flattening, conventional production steps are used so as to form the light shielding film 4, and thereafter, a P-SiN layer is thickly deposited as the passivation film 5 by using a CVD technique or the like.

Thereafter, SOG is applied to a top surface of the passivation film 5 and a top surface of the resultant film is etched by using an RIE under an etching condition such that the selectivity ratio of the P-SiN to the SOG is about 1:1, thereby flattening the top surface of the passivation film 5. More particularly, the light shielding film 4 is deposited so as to have a thickness of about 3000 Å to 10000 Å, and a P-SiN film having a thickness of about 20000 Å is deposited as the passivation film 5. SOG is applied to the P-SiN film so as to have a thickness of about 15000 Å. A 1:1 selectivity ratio of P-SiN to SOG can be obtained under the following RIE etching conditions: pressure: 4 to 15 Pa; CHF₃: 20 to 50 sccm; CF₄: 20 to 50 sccm; Ar: 50 to 100 sccm; O₂: 1 to 5 sccm; and RF: 200 to 700 W. By performing etching under such conditions, the top surface of the P-SiN film can be flattened (Figure 3E). After flattening the top surface

of the passivation film 5, a planarization film 6 is formed by applying an acrylic material to the passivation film 5. In the case of a color solid-state imaging device, an acrylic material is applied; a color filter is formed; and then the acrylic material is further applied thereto as a protection coating, thereby completing the planarization film 6. Thereafter, a lens material is applied to the planarization film 6, and the microlens 7 is formed by patterning and heat treatment (Figure 3F).

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Since the stepped portions of the passivation film 5 are eliminated, the aperture of the light shielding film 4 can be represented as (pixel size) - (width of light shielding film). For example, in the case where the width of the light shielding film 4 is $1.5\text{ }\mu\text{m}$, given a pixel size of $5\text{ }\mu\text{m} \times 5\text{ }\mu\text{m}$, the aperture of the light shielding film 4 is calculated to be $5 - 1.5 = 3.5\text{ }\mu\text{m}$, and therefore, the numerical aperture is 70%. Since the conventional numerical aperture is 50%, the numerical aperture of the present example is improved so as to be 1.4 times the conventional numerical aperture.

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(Example 2)

Example 2 of the present invention will now be

described.

A basic structure of Example 2 of the present invention is shown in Figure 2. As shown in Figure 2, a light reception section 2 for converting incident light to an electric charge is formed on a top surface of a silicon substrate 1. An interlaminar insulation film 3 for electrically isolating a first metal layer 8, a second metal layer 9, and a light shielding film 4 from one another is formed on the silicon substrate 1. The light shielding film 4 is formed on the interlaminar insulation film 3 without overlying a light reception face of the light reception section 2, so that incident light does not fall anywhere except the light reception section 2. A silicon oxide film 10 is formed on the light shielding film 4 and on the interlaminar insulation film 3 which is present within an aperture of the light shielding film 4. A portion of the silicon oxide film 10 is removed, to such an extent that the light shielding film 4 is not exposed, by using chemical machine polishing. Thus a surface of the silicon oxide film 10 is flattened. When the silicon oxide film 10 is formed by application of SOG, a silicon oxide film having a flat top surface can be formed without performing chemical machine polishing. A

passivation film 5 is formed on the silicon oxide film 10 in order to provide moisture-resistance, chemical resistance, and improved barrier properties against impurities such as Na ions, oxygen, etc., and metals. A
5 planarization film 6 is formed on the passivation film 5. A microlens 7 is formed for converging light which is incident on the planarization film 6.

In Example 2, because it is more advantageous to
10 flatten the top surface of the silicon oxide-based film than to flatten the top surface of the P-SiN film, it is easier to apply chemical machine polishing to the silicon oxide film 10 than to the P-SiN passivation film 5 for the following reasons. Firstly, a silicon oxide-based
15 film can be relatively easily etched since its etching rate is faster than that of the P-SiN film. Secondly, since chemical machine polishing is performed at the time of forming the interlaminar insulation film 3, a conventional chemical machine polishing technique can be
20 applied to the silicon oxide-based film. Since the passivation film 5 is deposited on the silicon oxide film 10 after the top surface of the silicon oxide film 10 is flattened, a top surface of the passivation film 5 can also be flattened. Thus, the stepped portion of the

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A method for producing a solid-state imaging device according to Example 2 will now be described with reference to Figure 4. Production steps of the conventional method and Example 1 are used in Example 2 so as to form the light shielding film 4. The light reception section 2 is formed in the silicon substrate 1 through ion implantation, heat treatment, etc. (Figure 4A). After forming a polycrystalline silicon film and a silicide film on the silicon substrate 1 by using a CVD technique, a gate electrode (not shown) is formed by patterning, etching, or the like. Thereafter, a BPSG film having a thickness of about 5000 Å to 15000 Å is deposited as the interlaminar insulation film 3 by a CVD technique. By subjecting the BPSG film to heat treatment at about 850 to 950°C, its surface is flattened so as to facilitate the formation of the first metal layer 8. The first metal layer 8 is formed by depositing TiN to a thickness of about 300 Å to 1000 Å and Al to a thickness of about 3000 Å to 10000 Å on the BPSG film by

using a sputtering or CVD technique (Figure 4B). Upon the first metal layer 8, a P-SiO₂ film having a thickness of about 20000 Å to 25000 Å is deposited as the interlaminar insulation film 3 by using a CVD technique, and a thickness of about 10000 Å is removed from the P-SiN film by chemical machine polishing, thereby flattening the film surface. Thereafter, as in the case of the first metal layer 8, TiN having a thickness of about 300 Å to 1000 Å and Al having a thickness of about 3000 Å to 10000 Å are deposited as the second metal layer 9 by using a sputtering or CVD technique (Figure 4C). Similarly, upon the second metal layer 9, a P-SiO₂ film having a thickness of about 20000 Å to 25000 Å is deposited as the interlaminar insulation film 3 by using a CVD technique, and a thickness of about 10000 Å is removed from the P-SiO₂ film by chemical machine polishing, thereby flattening the film surface. Thereafter, TiN having a thickness of about 300 Å to 1000 Å and Al having a thickness of about 3000 Å to 10000 Å are deposited as the light shielding film 4 by using a sputtering or CVD technique, and the resultant film is patterned and etched so as not to overlie the light reception section 2 (Figure 4D). As described above, production steps of the conventional method are used so as to form the light shielding film 4. Thereafter,

the silicon oxide film 10 having a thickness of about 20000 Å to 25000 Å is deposited by using a CVD technique and a thickness of about 10000 Å is removed from the resultant film by a chemical machine polishing (Figure 4E). Thereafter, a P-SiN film 5 having a thickness of about 3000 Å to 10000 Å is deposited on the silicon oxide film 10, thereby flattening a top surface of the P-SiN film 5 (Figure 4F).

In another way of flattening, conventional production steps are used so as to form the light shielding film 4, and thereafter, SOG is applied to the light shielding film 4 as the silicon oxide film 10 (Figure 4E). A P-SiN film 5 is deposited on the flattened silicon oxide film 10, which is formed of an SOG film, so as to obtain the P-SiN film 5 having a flat top surface (Figure 4F). In this case, the applied SOG film has a thickness of about 10000 Å to 15000 Å, and the P-SiN film 5 having a thickness of about 3000 Å to 10000 Å is deposited by a CVD technique. Thereafter, the planarization film 6 is formed by applying an acrylic material to the P-SiN film 5. In the case of a color solid-state imaging device, an acrylic material is applied; a color filter is formed; and then the acrylic material is further applied thereto

as a protection coating, thereby completing the planarization film 6. Thereafter, a lens material is applied thereto and the microlens 7 is formed by patterning and heat treatment (Figure 4G).

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As described above, according to the present invention, the stepped portion can be eliminated by flattening a top surface of the passivation film, so that incident light can be converged on the light reception section. Therefore, the present invention makes it possible to provide a solid-state imaging device which is capable of efficiently converging incident light on a light reception section thereof so as to be adapted for reduced pixel size.

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Various other modifications will be apparent to and can be readily made by those skilled in the art without departing from the scope and spirit of this invention. Accordingly, it is not intended that the scope of the claims appended hereto be limited to the description as set forth herein, but rather that the claims be broadly construed.

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